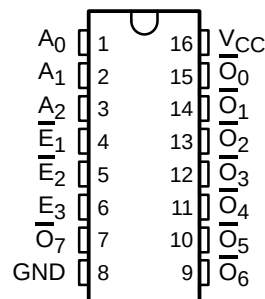
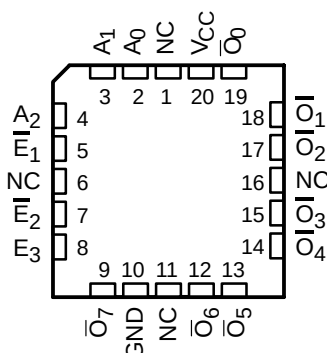


- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- Dual 1-of-8 Decoder With Enables
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- CY54FCT138T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT138T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

CY54FCT138T . . . D PACKAGE
CY74FCT138T . . . Q OR SO PACKAGE
(TOP VIEW)



CY54FCT138T . . . L PACKAGE
(TOP VIEW)



NC – No internal connection

description

The 'FCT138T devices are 1-of-8 decoders. These devices accept three binary weighted inputs (A_0 , A_1 , A_2) and, when enabled, provide eight mutually exclusive active-low outputs ($\overline{O}_0$ – $\overline{O}_7$). The 'FCT138T devices feature three enable inputs: two active low ($\overline{E}_1$, $\overline{E}_2$) and one active high (E_3).

All outputs are high unless $\overline{E}_1$ and $\overline{E}_2$ are low and E_3 is high. This multiple-enable function allows easy parallel expansion of the device to a 1-of-32 (five lines to 32 lines) decoder with just four 'FCT138T devices and one inverter.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	DESCRIPTION
A	Address inputs
$\overline{E}_1$, $\overline{E}_2$	Enable inputs (active low)
E_3	Enable input (active high)
$\overline{O}$	Outputs



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CY54FCT138T, CY74FCT138T 1-OF-8 DECODERS

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ORDERING INFORMATION

T _A	PACKAGE [†]		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	5	CY74FCT138CTQCT	FT138-3
	SOIC – SO	Tube	5	CY74FCT138CTSOC	FCT138C
		Tape and reel	5	CY74FCT138CTSOCT	
	QSOP – Q	Tape and reel	5.8	CY74FCT138ATQCT	FT138-1
	SOIC – SO	Tube	5.8	CY74FCT138ATSOC	FCT138A
		Tape and reel	5.8	CY74FCT138ATSOCT	
–55°C to 125°C	QSOP – Q	Tape and reel	9	CY74FCT138TQCT	FT138
	LCC – L	Tube	6	CY54FCT138CTLMB	
	LCC – L	Tube	12	CY54FCT138TLMB	
	CDIP – D	Tube	12	CY54FCT138TDMB	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS						OUTPUTS							
$\overline{E}_1$	$\overline{E}_2$	E ₃	A ₀	A ₁	A ₂	$\overline{O}_0$	$\overline{O}_1$	$\overline{O}_2$	$\overline{O}_3$	$\overline{O}_4$	$\overline{O}_5$	$\overline{O}_6$	$\overline{O}_7$
H	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	L	X	X	X	H	H	H	H	H	H	H	H
L	L	H	L	L	L	L	H	H	H	H	H	H	H
L	L	H	H	L	L	H	L	H	H	H	H	H	H
L	L	H	L	H	L	H	H	L	H	H	H	H	H
L	L	H	H	H	L	H	H	H	L	H	H	H	H
L	L	H	L	H	H	H	H	H	H	L	H	H	H
L	L	H	H	H	H	H	H	H	H	H	L	H	H
L	L	H	L	H	H	H	H	H	H	H	H	L	H
L	L	H	H	H	H	H	H	H	H	H	H	H	L

H = High logic level, L = Low logic level, X = Don't care



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The diagram illustrates a 3-to-8 decoder implemented using NAND gates. The inputs are A_0 , A_1 , and A_2 . The outputs are labeled $\overline{O}_0$ through $\overline{O}_7$. The circuit uses a combination of NAND gates and inverters to generate the eight output signals. The inputs A_0 , A_1 , and A_2 are connected to three NAND gates (labeled 1, 2, 3) to produce outputs $\overline{O}_0$ through $\overline{O}_7$. The diagram shows the internal wiring of the decoder, including the use of inverters and NAND gates to generate the eight output signals.

NOTE 1: The package thermal impedance is calculated in accordance with JEDEC 51-7.

CY54FCT138T, CY74FCT138T

1-OF-8 DECODERS

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recommended operating conditions (see Note 2)

	CY54FCT138T			CY74FCT138T			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
I _{OH} High-level output current			–12			–32	mA
I _{OL} Low-level output current			32			64	mA
T _A Operating free-air temperature	–55		125	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	CY54FCT138T			CY74FCT138T			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _{IN} = –18 mA		–0.7	–1.2				V
	V _{CC} = 4.75 V, I _{IN} = –18 mA					–0.7	–1.2	
V _{OH}	V _{CC} = 4.5 V, I _{OH} = –12 mA	2.4	3.3					V
	V _{CC} = 4.75 V				2			
					2.4	3.3		
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 32 mA		0.3	0.55				V
	V _{CC} = 4.75 V, I _{OL} = 64 mA					0.3	0.55	
V _{hys}	All inputs		0.2			0.2		V
I _I	V _{CC} = 5.5 V, V _{IN} = V _{CC}			5				μA
	V _{CC} = 5.25 V, V _{IN} = V _{CC}						5	
I _{IH}	V _{CC} = 5.5 V, V _{IN} = 2.7 V			±1				μA
	V _{CC} = 5.25 V, V _{IN} = 2.7 V						±1	
I _{IL}	V _{CC} = 5.5 V, V _{IN} = 0.5 V			±1				μA
	V _{CC} = 5.25 V, V _{IN} = 0.5 V						±1	
I _{OS} ‡	V _{CC} = 5.5 V, V _{OUT} = 0 V	–60	–120	–225				mA
	V _{CC} = 5.25 V, V _{OUT} = 0 V				–60	–120	–225	
I _{off}	V _{CC} = 0 V, V _{OUT} = 4.5 V			±1			±1	μA
I _{CC}	V _{CC} = 5.5 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} – 0.2 V		0.1	0.2				mA
	V _{CC} = 5.25 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} – 0.2 V					0.1	0.2	
ΔI _{CC}	V _{CC} = 5.5 V, V _{IN} = 3.4 V [§] , f ₁ = 0, Outputs open		0.5	2				mA
	V _{CC} = 5.25 V, V _{IN} = 3.4 V [§] , f ₁ = 0, Outputs open					0.5	2	
I _{CCD} ¶	V _{CC} = 5.5 V, Outputs open, One bit switching at 50% duty cycle, V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V		0.06	0.12				mA/ MHz
	V _{CC} = 5.25 V, Outputs open, One bit switching at 50% duty cycle, V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V					0.06	0.12	

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

¶ This parameter is derived for use in total power-supply calculations.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS			CY54FCT138T			CY74FCT138T			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
I _C [#]	V _{CC} = 5.5 V, Outputs open, Switch $\bar{E}_1$, $\bar{E}_2$, or E ₃	One output switching at f ₁ = 10 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V	0.7	1.4				mA	
			V _{IN} = 3.4 V or GND	1	2.4					
	V _{CC} = 5.25 V, Outputs open, Switch $\bar{E}_1$, $\bar{E}_2$, or E ₃	One output switching at f ₁ = 10 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V			0.7	1.4			
			V _{IN} = 3.4 V or GND			1	2.4			
C _i				5	10	5	10		pF	
C _O				9	12	9	12		pF	

† Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY54FCT138T		CY54FCT138CT		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	$\bar{O}$	1.5	12	1.5	6	ns
t_{PHL}			1.5	12	1.5	6	
t_{PLH}	$\bar{E}_1$ or $\bar{E}_2$	$\bar{O}$	1.5	12.5	1.5	6.1	ns
t_{PHL}			1.5	12.5	1.5	6.1	
t_{PLH}	E_3	$\bar{O}$	1.5	12.5	1.5	6.1	ns
t_{PHL}			1.5	12.5	1.5	6.1	

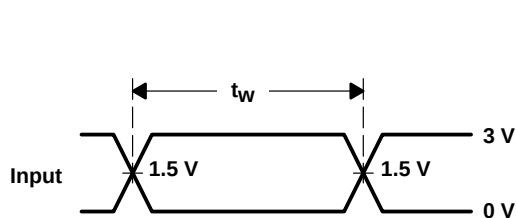
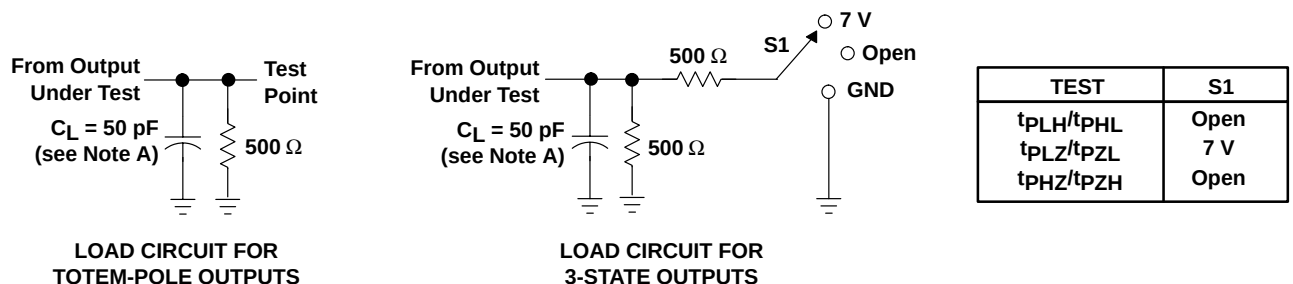
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT138T		CY74FCT138AT		CY74FCT138CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	$\bar{O}$	1.5	9	1.5	5.8	1.5	5	ns
t_{PHL}			1.5	9	1.5	5.8	1.5	5	
t_{PLH}	$\bar{E}_1$ or $\bar{E}_2$	$\bar{O}$	1.5	9	1.5	5.9	1.5	5	ns
t_{PHL}			1.5	9	1.5	5.9	1.5	5	
t_{PLH}	E_3	$\bar{O}$	1.5	9	1.5	5.9	1.5	5	ns
t_{PHL}			1.5	9	1.5	5.9	1.5	5	

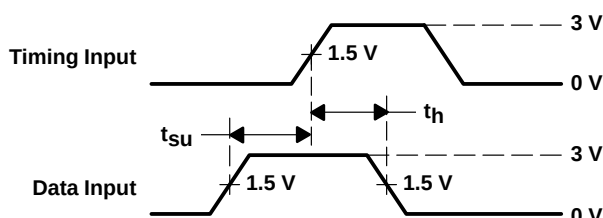
CY54FCT138T, CY74FCT138T 1-OF-8 DECODERS

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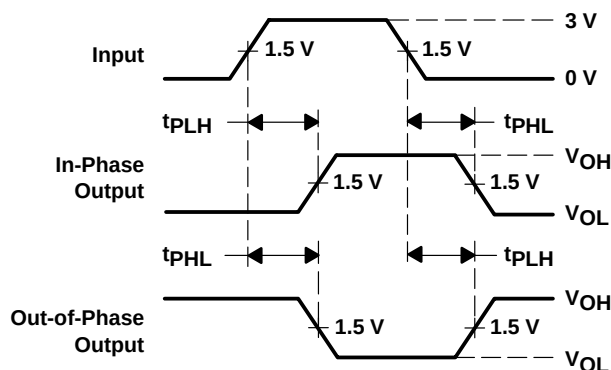
PARAMETER MEASUREMENT INFORMATION



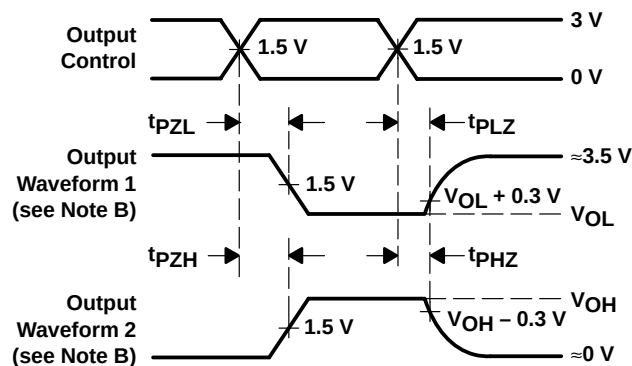
**VOLTAGE WAVEFORMS
PULSE DURATION**



**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9223302M2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9223302MEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-9223306M2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9223306MEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CY54FCT138CTLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
CY54FCT138TDMB	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CY54FCT138TLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
CY74FCT138ATQCT	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138ATQCTE4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138ATQCTG4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138ATSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138ATSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138ATSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138ATSOCT	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138ATSOCTE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138ATSOCTG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138CTQCT	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138CTQCTE4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138CTQCTG4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138CTSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CY74FCT138CTSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138CTSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CY74FCT138TQCT	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138TQCTE4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
CY74FCT138TQCTG4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

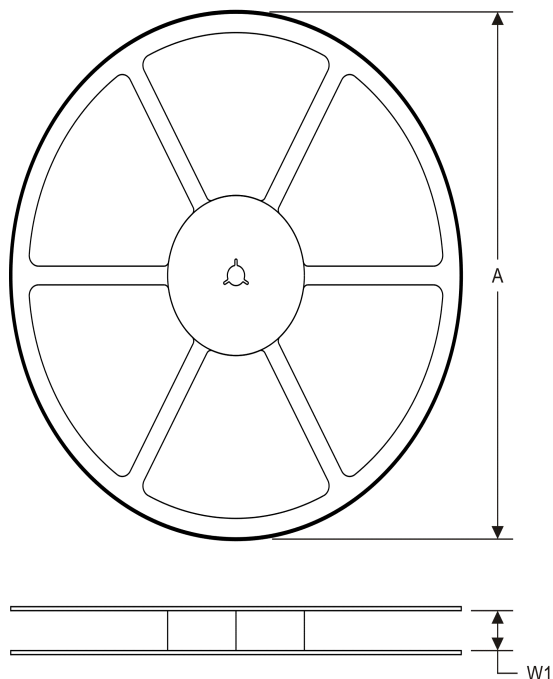
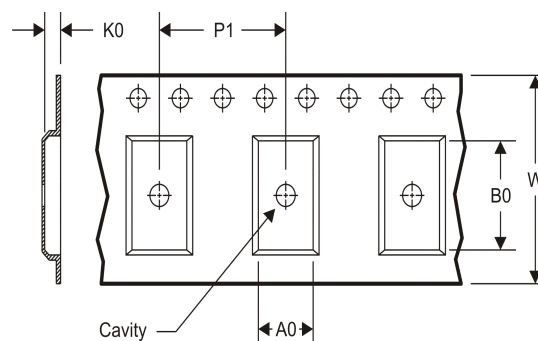
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


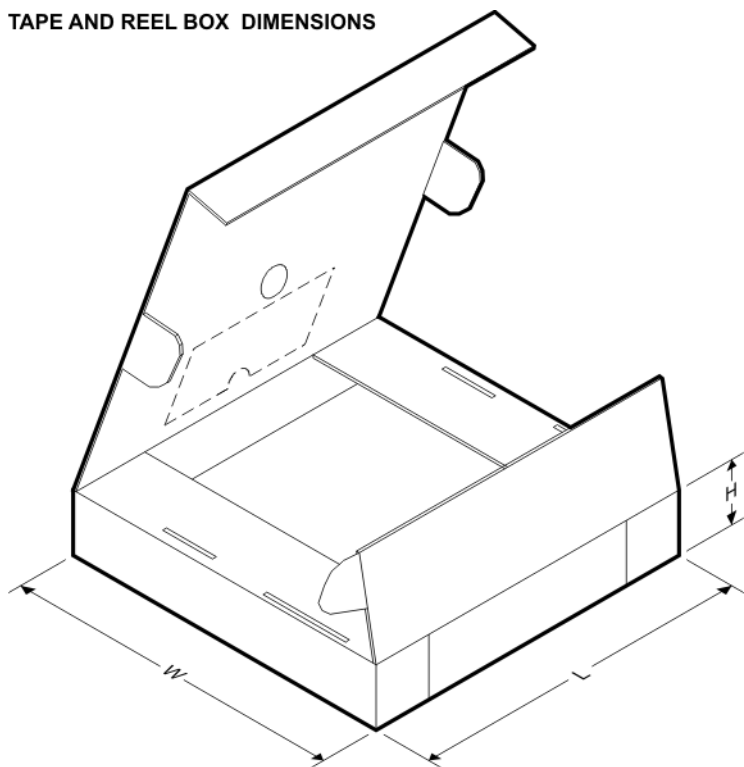
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT138ATSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT138ATSOCT	SOIC	DW	16	2000	367.0	367.0	38.0

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